

N-Ch MOSFET

General Description

The WSP08N10 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSF08N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

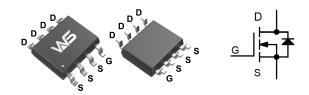
Product Summery

BVDSS	RDSON	ID
100V	39mΩ	7.0A

Applications

• Power Management in DC/DC Converter.

SOP-8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter Rating		Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	7.0	Α
I _D @T _C =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	5.5	А
I _{DM}	Pulsed Drain Current ²	28	Α
EAS	Single Pulse Avalanche Energy ³	60	mJ
I _{AS}	Avalanche Current	9	Α
P _D @T _A =25℃	Total Power Dissipation⁴	2.5	W
T _{STG}	Storage Temperature Range -55 to 15		$^{\circ}$
TJ	Operating Junction Temperature Range -55 to 150		$^{\circ}$

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-ambient ¹		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		24	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃, I _D =1mA		0.098		V/℃
В	2	V _{GS} =10V , I _D =7A		39	51	0
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =4A		44	57	mΩ
$V_{GS(th)}$	Gate Threshold Voltage)/ -\/ -250\	2.0	3.0	4.0	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-5.52		mV/℃
	Drain Source Loakage Current	V_{DS} =80V , V_{GS} =0V , T_J =25 $^{\circ}\mathrm{C}$			10	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =55℃			100	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.6	3.2	Ω
Qg	Total Gate Charge (10V)			40		
Q _{gs}	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =7A		6		nC
Q _{gd}	Gate-Drain Charge			7		
T _{d(on)}	Turn-On Delay Time			11	20	
Tr	Rise Time	V_{DD} =30V , V_{GEN} =10V , R_G =6 Ω		9	17	20
$T_{d(off)}$	Turn-Off Delay Time	I _D =1A ,R _L =30Ω		60	113	ns
T _f	Fall Time			30	56	
C _{iss}	Input Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		1600		
Coss	Output Capacitance			120		pF
C _{rss}	Reverse Transfer Capacitance			75		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.3mH , I _{AS} =9A	50			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			6	Α
I _{SM}	Pulsed Source Current ^{2,6}				28	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =6A , T _J =25℃			1.1	V
t _{rr}	Reverse Recovery Time	-IF=7A, dI/dt=100A/μs,Tյ=25℃		61		nS
Q _{rr}	Reverse Recovery Charge			127		nC

Note

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.3mH,I_{AS}=9A
- 4.The power dissipation is limited by 150 $^{\circ}\mathrm{C}$ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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Typical Characteristics

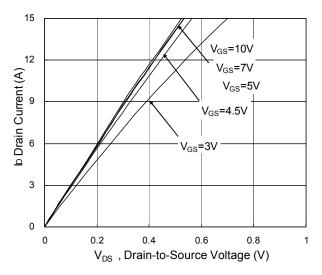


Fig.1 Typical Output Characteristics

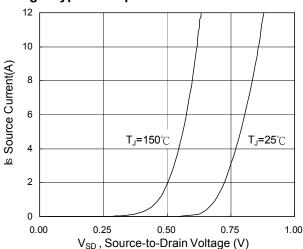


Fig.3 Forward Characteristics Of Reverse

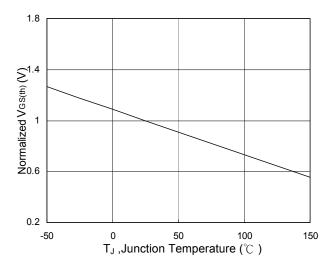


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

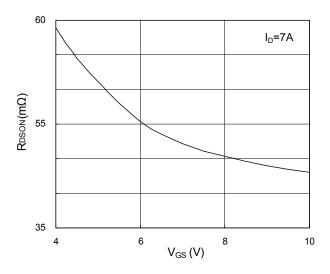


Fig.2 On-Resistance vs. Gate-Source

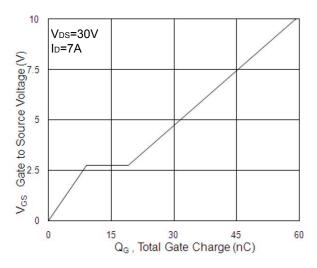


Fig.4 Gate-Charge Characteristics

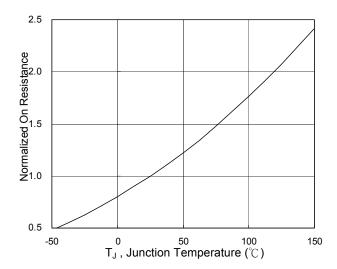
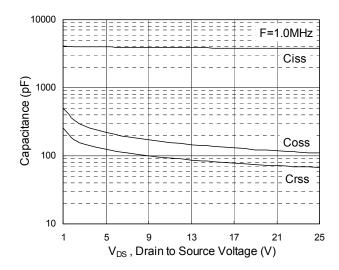


Fig.6 Normalized R_{DSON} vs. T_J





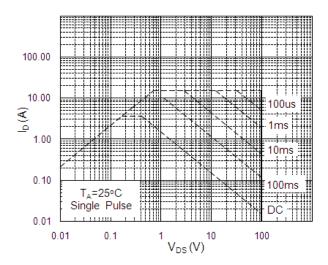


Fig.7 Capacitance

Fig.8 Safe Operating Area

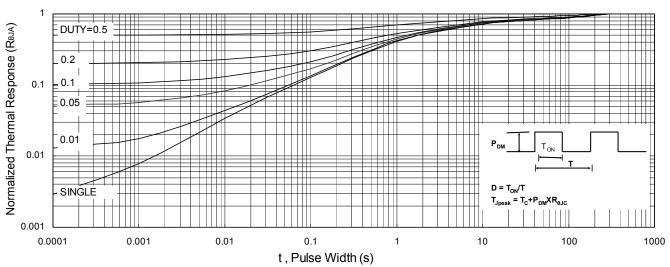


Fig.9 Normalized Maximum Transient Thermal Impedance

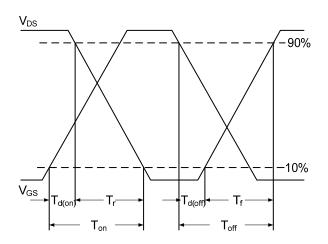


Fig.10 Switching Time Waveform

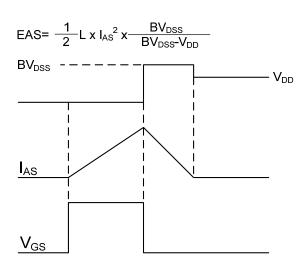


Fig.11 Unclamped Inductive Switching Waveform



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